

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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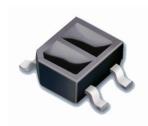


DATASHEET

EAITRCA8

Features

- Fast response time
- High sensitivity
- Cut-Off visible wavelength
- Thin
- Compact
- Pb free



Description

• EAITRCA8 is a light reflection switch which includes a GaAs IR-LED transmitter and a NPN photo-transistor with a high photosensitive receiver for short distance, operating in the infrared range. Both components are mounted side-by-side in a plastic package.

Applications

- Camera
- VCR
- Floppy disk driver
- Cassette type recorder
- Various microcomputer control equipment



Device Selection Guide

Device No.	Chip Material
IR	GaAlAs
PT	Silicon

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit
Input	Power Dissipation at(or below) 25°C Free Air Temperature	Pd	75	mW
	Reverse Voltage	VR	6	V
	Forward Current	IF	50	mA
	Peak Forward Current (*1) Pulse width ≤100μs, Duty cycle=1%	IFP	1	A
Output	Collector Power Dissipation	Pc	100	mW
	Collector Current	Ic	20	mA
	Collector-Emitter Voltage	B VCEO	35	V
	Emitter-Collector Voltage	B Veco	6	V
Operating Temperature		Topr	-25~+85	$^{\circ}\mathbb{C}$
Storage Temperature		Tstg	-30~+90	$^{\circ}\mathbb{C}$
Lead Soldering Temperature (*2) (1/16 inch form body for 5 seconds)		Tsol	260	$^{\circ}\!\mathbb{C}$

Notes: (*1) tw=100 µsec., T=10 msec. (*2) t=10 Sec

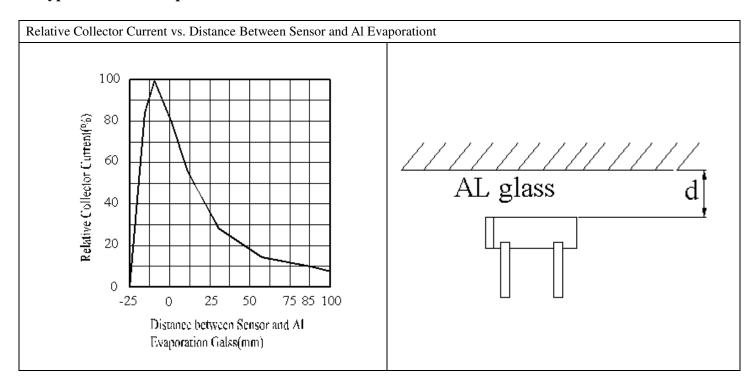


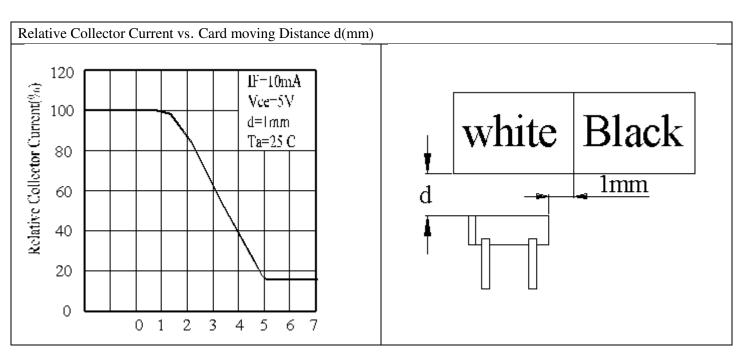
Electro-Optical Characteristics (Ta=25 $^{\circ}$ C)

Parameter		Symbol	Min.	Тур.	Max.	Unit	Conditions	
Input	Forward Voltage	V_{F}		1.2	1.4	V	I _F =20mA	
	Reverse Current	I_R			10	μΑ	V _R =6V	
	Peak Wavelength	$\lambda_{ ext{P}}$		940		nm	I _F =10mA	
Output	Dark C urrent	I_{CEO}			100	nA	V _{CE} =10V	
Transfer Characteristics	Collect Current	$I_{C}(ON)$	0.5		15.0	mA	V _{CE} =2V, I _F =4mA	
	Leakage Current	ICEOD		1	5	μA	V _{CE} =2V, I _F =4mA	
	Rise time	t_r	1	ı	400	μs	$V_{CE} = 2V$ $I_{C} = 10mA$ $R_{L} = 100\Omega, d = 1mm$	
	Fall time	${f t}_{ m f}$	-	-	400	μs		

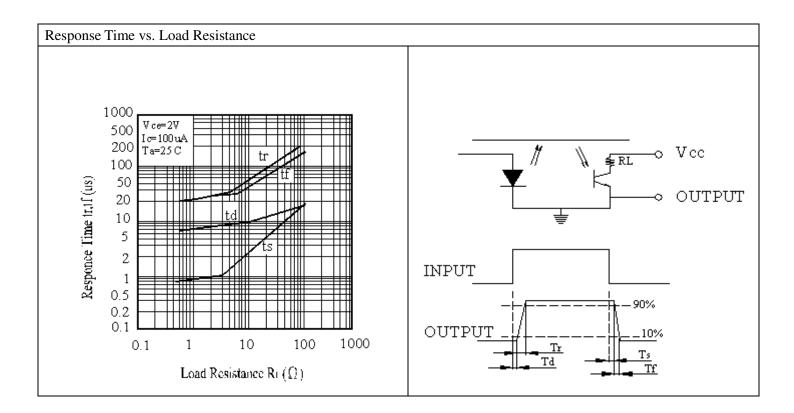


Typical Electrical/Optical/Characteristics Curves for ITR







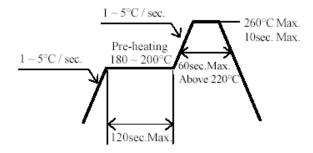




Recommended Method of Storage

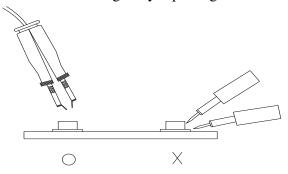
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- Shelf life in sealed bag: 12 months at < 40 °C and < 90% relative humidity (RH)
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must a) Mounted within 72 hours of factory conditions < 30 °C/60%RH, or b) Stored at <20% RH
- Devices require bake, before mounting, if:
 Humidity Indicator Card is > 20% when read at 23 ± 5 °C
- If baking is required, devices may be baked:
 - a) 192 hours at 40° C, and <5% RH(dry air/nitrogen) or
 - b) 96 hours at 60°C, and <5% RH for all device containers
 - c) 24 hours at 125 °C
- Soldering Condition
 - a) Pb-free solder temperature profile



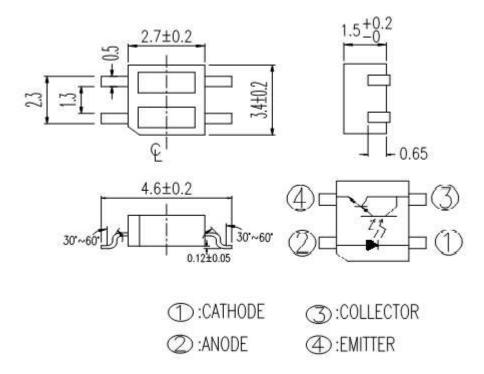
- b) Reflow soldering should not be done more than two times.
- c) When soldering, do not put stress on the LEDs during heating.
- d) After soldering, do not warp the circuit board.
- Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Package Dimension



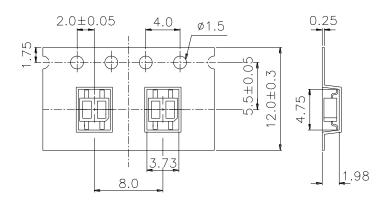
Notes: 1. All dimensions are in millimeters

2. Tolerances unless dimensions ±0.25mm



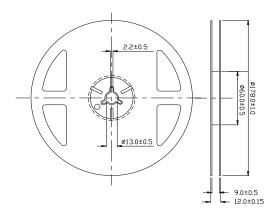
Taping Dimension

Progressive direction _

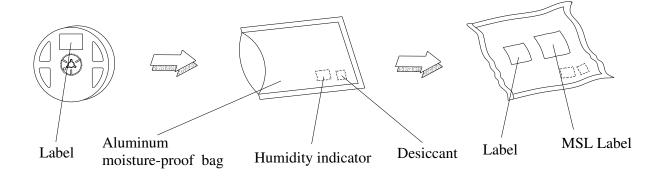


General Tolerance ±0.1 UNIT:mm

Reel Dimensions



Moisture Resistant Packaging

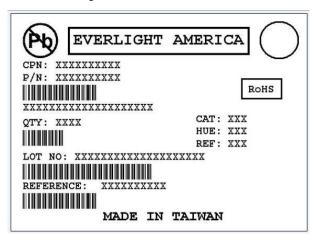




Packing Quantity Specification

- 1. 1000 Pcs/ 1Reel
- 2. 15 Reel /1 Box
- 3. 2 Box/ 1 Carton

Label Form Specification



- CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number
- X: Month
- Reference: Identify Label Number

Notes

- 1. Above specification may be changed without notice. EVERLIGHT Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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